



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: 147268.00254

Group Art Unit: 2814

Examiner: Dilinh P. Nguyen

Inventors: Jung-Yu Lee *et al.*

Serial No.: 09/746,018

Filed: December 26, 2000

For: STRUCTURE OF HEAT SLUG-EQUIPPED PACKAGES AND THE PACKAGING METHOD OF THE SAME

#13/Amct#D
5/6/03
C.P.
**REPLACEMENT
AMENDMENT**

**APPLICANTS'
RESPONSIVE
AMENDMENT-B**

Hon. Commissioner of Patents
And Trademarks
Washington, D.C. 20231

Sir:

In response to the Notice of Non-Compliant Amendment (37 C.F.R. 1.121) mailed December 6, 2002, and in response Office Action mailed September 25, 2002, please amend the above-identified application as follows.

IN THE SPECIFICATION:

Please amend the paragraph at page 6, lines 11 through 19, to correct an obvious typographical error as follows:

D' Again in FIG. 3, the chip (die) 22 and the substrate 20 are interconnected by means of signal transferring means such as bonding wires 26, which can be, for example, gold wires. Actually, the die 22 is connected to the conductive traces on the substrate 20. Using conventional wire bonding or